Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.6 EP)
Lead Count	32
Terminal Finish	100 Sn
MS Number	MS010587B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.31E-02	86.91	869100	38.44	384398
Thermosets	Epoxy & Phenol Resin	Proprietary	3.40E-03	12.78	127800	5.65	56525
Other inorganic materials	Carbon black	1333-86-4	8.24E-05	0.31	3100	0.14	1371
Subtotal			2.66 E-02	100.00	1000000	44.23	442294

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.82 E-02	97.50	975000	46.89	468896
Copper & its alloys	Iron	7439-89-6	6.79 E-04	2.35	23500	1.13	11302
Copper & its alloys	Zinc	7440-66-6	3.47 E-05	0.12	1200	0.06	577
Copper & its alloys	Phosphorus	7723-14-0	8.67 E-06	0.03	300	0.01	144
Subtotal			2.89 E-02	100.00	1000000	48.09	480919

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.89 E-04	100.0	1000000	0.48	4809

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.69 E-03	100.0	1000000	2.81	28061

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.18 E-04	99.0	990000	0.53	5298
Precious metals	Palladium	7440-05-3	3.22 E-06	1.0	10000	0.01	54
Subtotal			3.22 E-04	100.0	1000000	0.54	5352

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.03 E-03	100.0	1000000	3.38	33823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.21 E-04	77.71	777100	0.37	3684
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	8.86 E-06	3.11	31100	0.01	147
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	8.86 E-06	3.11	31100	0.01	147
Other organic materials	Butyrolactone, gamma-	96-48-0	8.86 E-06	3.11	31100	0.01	147
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	8.86 E-06	3.11	31100	0.01	147
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	8.86 E-06	3.11	31100	0.01	147
Other organic materials	Organosilane	TS ref# 10001	8.86 E-06	3.11	31100	0.01	147
Other inorganic materials	Copper(II) oxide	1317-38-0	8.86 E-06	3.11	31100	0.01	147
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.48 E-06	0.52	5200	0.002	25
Subtotal			2.85 E-04	100.0	1000000	0.47	4741

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.01 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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